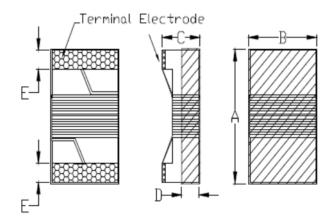


FEATRLRES

- Monolithic inorganic material construction.
- Closed magnetic circuit avoids crosstalk.
- S.M.T. type.
- Suitable for reflow soldering.
- Shapes and dimensions follow E.I.A. spec.
- Available in various sizes.
- Excellent solder ability and heat resistance.
- High reliability.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

CONFIGRLRATIONS & DIMENSIONS (unit in mm)



Size	A	В	С	D	E
SWF2520	2.9max	2.5max	2.1max	1.2ref.	0.55±0.1

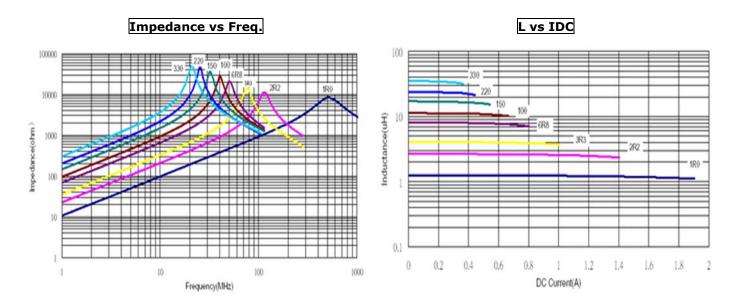
ELECTRICAL CHARACTERISTICS

Part Number	Inductance	Tolerance	Test Frequency	Q	Test Frequency	Rated	DCR(Ω)	SRF
rai (Nullibei	(uH)	Toterance	(Hz)	min.	(MHz)	Current(mA)	max.	(MHz)min.
SWF2520CF-1R0K	1.00±10%	K,M	0.5V/7.96M	12	7.96	1000	0.13	345
SWF2520CF-1R5K	1.50±10%	K,M	0.5V/7.96M	12	7.96	850	0.17	100
SWF2520CF-2R2K	2.20±10%	K,M	0.5V/7.96M	12	7.96	775	0.21	78
SWF2520CF-3R3K	3.30±10%	K,M	0.5V/7.96M	12	7.96	715	0.26	48
SWF2520CF-4R7K	4.70±10%	K,M	0.5V/7.96M	12	7.96	505	0.52	46
SWF2520CF-6R8K	6.80±10%	K,M	0.5V/7.96M	12	7.96	432	0.72	33
SWF2520CF-8R2K	8.20±10%	J,K	0.5V/2.52M	12	2.52	410	0.76	30
SWF2520CF-100K	10.0±10%	K,M	0.5V/2.52M	12	2.52	392	0.86	28
SWF2520CF-150K	15.0±10%	K,M	0.5V/2.52M	12	2.52	342	1.09	21
SWF2520CF-220K	22.0±10%	K,M	0.5V/2.52M	12	2.52	260	1.96	18
SWF2520CF-330K	33.0±10%	K,M	0.5V/2.52M	12	2.52	236	2.47	15

- NOTE: $K=\pm 10\%, L=\pm 15\%, M=\pm 20\%$
- Rated current: based on temperature rise test
- In compliance with EIA 595



Impedance vs Frequency, DC Bias Characteristics (Typical)



Reliability and Test Condition

Item	Performance	Test Condition			
Operating temperature	-40~+125℃ (Including self - temperature rise)				
Storage temperature	110~+40℃,50~60%RH (Product with taping) 240~+125℃ (on board)				
Electrical Performance Test					
Inductance	Refer to standard electrical characteristics list	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.			
DCR	Refer to standard electrical characteristics list.	CH16502,Agilent33420A Micro-Ohm Meter.			
Saturation Current (Isat)	Approximately∆L30%	Saturation DC Current (Isat) will cause L0 to drop △L(%)			
Heat Rated Current (Irms)	Approximately △T40°C	Heat Rated Current (Irms) will cause the coil temperature rise $\triangle T(^{\circ}C)$. 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer			
Reliability Test					
		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles) Temperature: 125±2°C (Inductor)			
Life Test		Applied current : rated current			
	Appearance : No damage.	Duration : 1000±12hrs Measured at room temperature after placing for 24±2 hrs			
Load Humidity	Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Humidity: 85±2 * R.H,			
	exceed the specification value	Temperature : 85°C±2°C Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs			



Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles 1. Baked at50 $^{\circ}$ C for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to $65\pm2^{\circ}$ C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25 $^{\circ}$ C in 2.5hrs. 3. Raise temperature to $65\pm2^{\circ}$ C 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25 $^{\circ}$ C in 2.5hrs heep at -10 $^{\circ}$ C for 3 hrs 4. Keep at 25 $^{\circ}$ C 90-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Condition for 1 cycle Step1: -40±2°C 30±5min Step2: 25±2°C ≤0.5min Step3: 125±2°C 30±5min Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations).
Bending		Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm <0805 inch(2012mm):40x100x0.8mm Bending depth: >=0805 inch(2012mm):1.2mm <0805 inch(2012mm):0.8mm duration of 10 sec.
Shock	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value	Type Peak value (g's) Normal duration (D) (ms) Wave form Velocity change (Vi)ft/sec SMD 50 11 Half-sine 11.3 Lead 50 11 Half-sine 11.3
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245±5°C ∘ Flux for lead free: Rosin. 9.5% ∘ Dip time: 4±1sec ∘ Depth: completely cover the termination
Resistance to Soldering Heat		Depth: completely cover the termination Temperature (°C) Time(s) Temperature ramp/immersion and emersion rate Number of heat cycles 260 ±5 (solder temp) 10 ±1 25mm/s ±6 mm/s 1
Terminal Strength	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD. 020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shal be applied gradually as not to apply a shock to the component being tested.

Note: When there are questions concerning measurement result: measurement shall be made after 48 ± 2 hours of recovery under the standard condition.